

BY228GP

SINTERED GLASS JUNCTION PLASTIC RECTIFIER

VOLTAGE:1500V

CURRENT: 3.0A

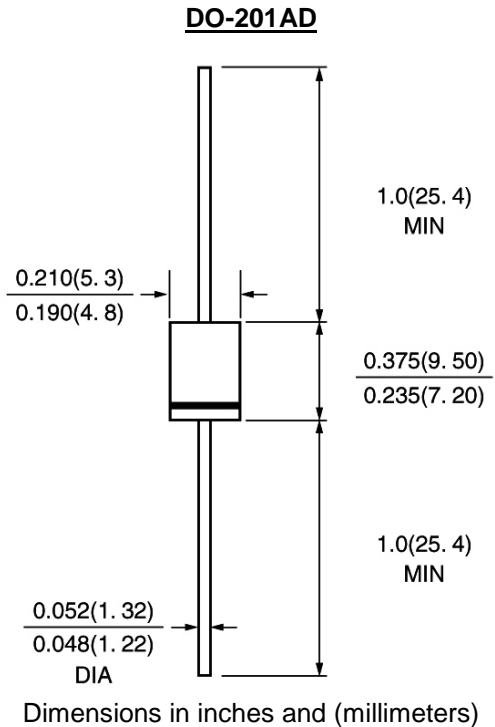


FEATURE

High temperature metallurgically bonded construction
Sintered glass cavity free junction
Capability of meeting environmental standard of MIL-S-19500
High temperature soldering guaranteed
350°C /10sec/0.375"lead length at 5 lbs tension
Operate at Ta =55°C with no thermal run away
Typical Ir<0.1μA

MECHANICAL DATA

Terminal:Plated axial leads solderable per MIL-STD 202E, method 208C
Case:Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy
Polarity:color band denotes cathode
Mounting position:any



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated, for capacitive load, derate current by 20%)

	SYMBOL	BY228GP	units
Maximum Recurrent Peak Reverse Voltage	V _{rrm}	1500	V
Maximum RMS Voltage	V _{rms}	1050	V
Maximum DC blocking Voltage	V _{dc}	1500	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =55°C	I _{f(av)}	3.0	A
Peak Forward Surge Current 8.3ms single Half sine-wave superimposed on rated load	I _{fsm}	125.0	A
Maximum Instantaneous Forward Voltage At 5.0A	V _f	1.50	V
Maximum full load reverse current full cycle Average at 55°C	I _{r(av)}	100.0	μA
Maximum DC Reverse Current at rated DC blocking voltage	I _r	5.0 100.0	μA μA
Typical Reverse Recovery Time (Note 1)	T _{rr}	1000	nS
Typical Thermal Resistance (Note 2)	R _{th(ja)}	70.0	K/W
Storage and Operating Junction Temperature	T _{stg} , T _j	-65 to +175	°C

Note:

1. Reverse Recovery Condition I_f =0.5A, I_r =1.0A, I_{rr} =0.25A
2. Thermal Resistance from Junction to Ambient on PC board with spacing 25mm

